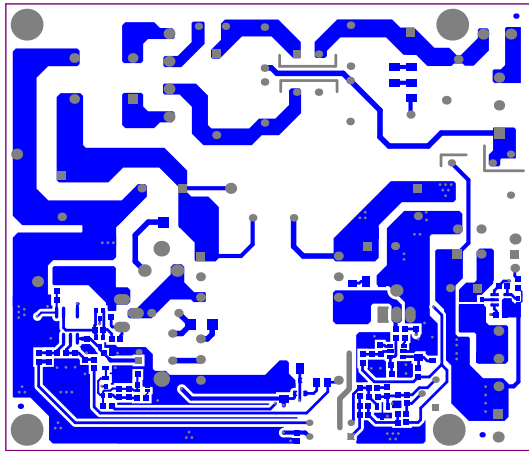
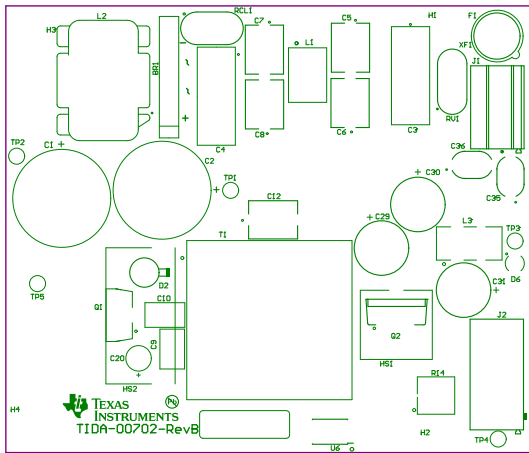


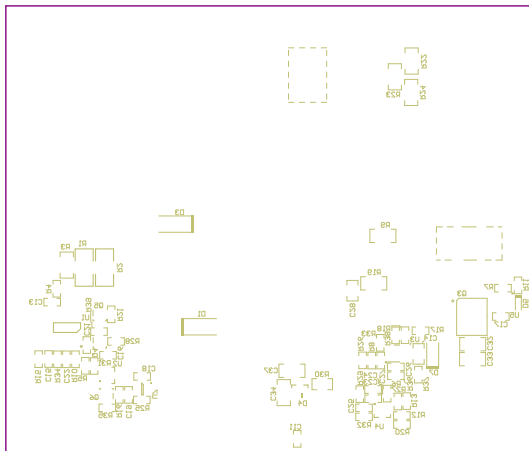
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/3/2015 5:35:33 PM	TEXAS INSTRUMENTS	



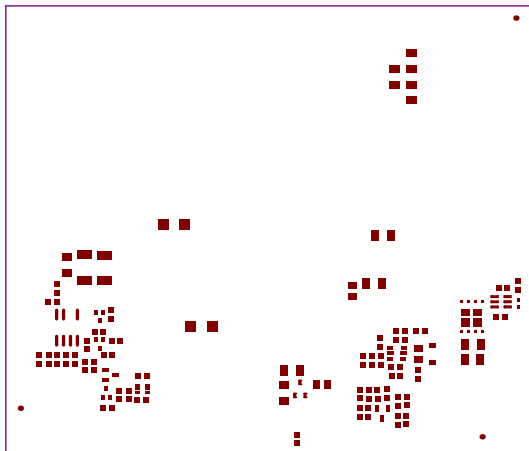
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/3/2015 5:35:34 PM	TEXAS INSTRUMENTS	



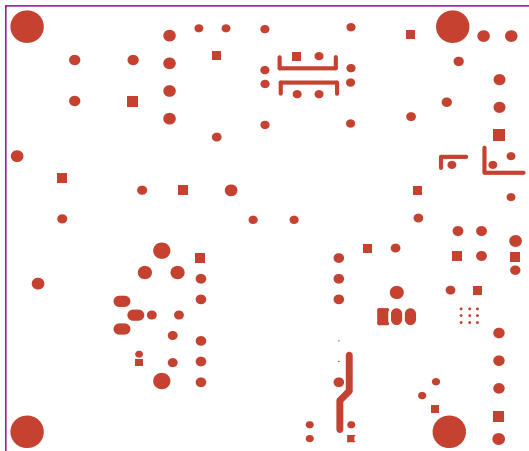
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Silkscreen Overlay	GENERATED : 12/3/2015 5:35:34 PM	TEXAS INSTRUMENTS	



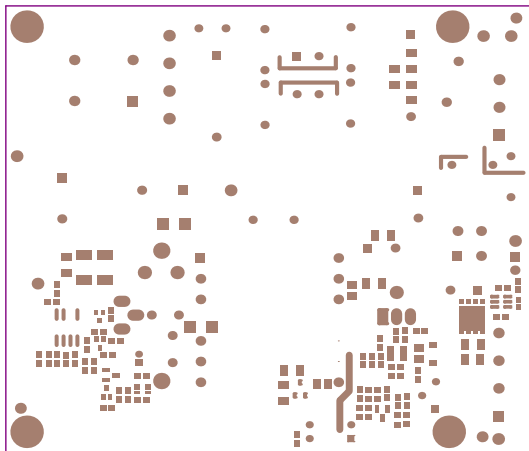
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 12/3/2015 5:35:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste			
PLOT NAME = Bottom Paste Mask Print	GENERATED : 12/3/2015 5:35:34 PM	TEXAS INSTRUMENTS	

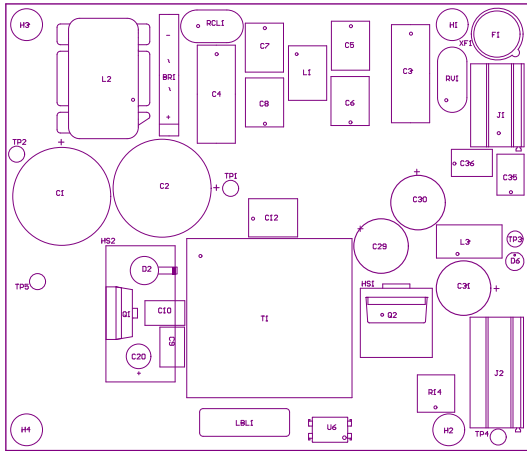


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask Print	GENERATED : 12/3/2015 5:35:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask Print	GENERATED : 12/3/2015 5:35:35 PM	TEXAS INSTRUMENTS	

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

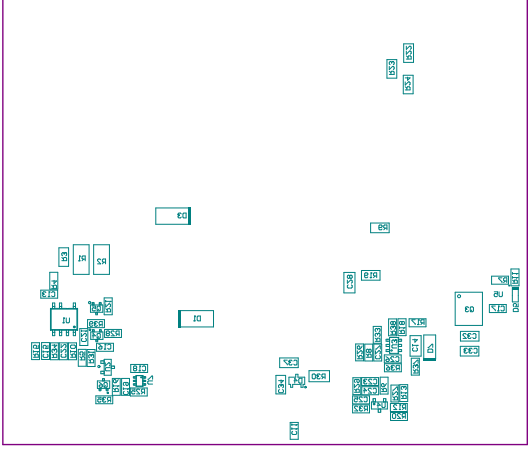


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
IGNORE -> M5 Assembly Top			
PLOT NAME = M5 Assembly Top	GENERATED : 12/3/2015 5:35:35 PM	TEXAS INSTRUMENTS	

PLOT NAME = MR Assembly Bottom	GENERATED : 12\3\2012 2:32:32 PM	TEXAS INSTRUMENTS
PCB VIEWED FROM BOTTOM SIDE	BOARD # : TIDA-00702	REV: RevB
	IGNORE -> MR Assembly Bottom	SUN REV: Not Recommended

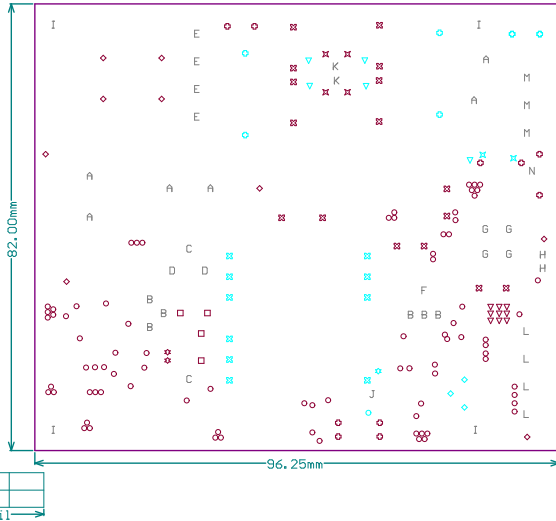
ASSEMBLY VARIANT (No Variants)
COMPONENTS MARKED 'DNP', SHOULD NOT BE POPULATED.



Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
∇	9	10mil (0.254mm)			PTH	Round
○	82	12mil (0.305mm)			PTH	Round
⊛	2	27.559mil (0.7mm)			PTH	Round
◇	3	28.11mil (0.714mm)			PTH	Round
□	4	31mil (0.787mm)			PTH	Round
○	10	33.465mil (0.85mm)			PTH	Round
⊞	4	33.622mil (0.854mm)			PTH	Round
⊞	16	35.433mil (0.9mm)			PTH	Round
H	2	35.984mil (0.914mm)			PTH	Round
○	8	39.37mil (1mm)			PTH	Round
◇	9	40mil (1.016mm)			PTH	Round
A	4	41.496mil (1.054mm)			PTH	Round
A	2	43.307mil (1.1mm)			PTH	Round
⊞	10	45.276mil (1.15mm)			PTH	Round
G	4	47.244mil (1.2mm)			PTH	Round
B	6	50mil (1.27mm)			PTH	Round
L	4	51.181mil (1.3mm)			PTH	Round
M	3	52mil (1.321mm)			PTH	Round
E	4	59.055mil (1.5mm)			PTH	Round
D	2	61.024mil (1.55mm)			PTH	Round
F	1	70.094mil (1.78mm)			PTH	Round
C	2	92.913mil (2.36mm)			PTH	Round
I	4	125mil (3.175mm)			PTH	Round
V	5	20mil (0.508mm)	100mil (2.54mm)	80mil (2.032mm)	NPTH	Slot
⊞	2	20mil (0.508mm)	200mil (5.08mm)	180mil (4.572mm)	NPTH	Slot
N	1	20mil (0.508mm)	300mil (7.62mm)	280mil (7.112mm)	NPTH	Slot
K	2	20mil (0.508mm)	425mil (10.795mm)	405mil (10.287mm)	NPTH	Slot
J	1	40mil (1.016mm)	120mil (3.048mm)	80mil (2.032mm)	NPTH	Slot
○	1	40mil (1.016mm)	250mil (6.35mm)	210mil (5.334mm)	NPTH	Slot
○	1	40mil (1.016mm)	300mil (7.62mm)	260mil (6.604mm)	NPTH	Slot
	208 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table
FOR 10MIL DRILL +0/-10MIL
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL



Notes
10mil Drill Vias are not Tented.
12mil Drill Vias are Tented in both sides.

Layer Name	Order	Material	Thickness	Dielectric Constant	Dielectric Type
Top Solder Mask	<GTS>	0.4mil	Solder Resist	3.50	
Top Layer	<GTL>	2.8mil	FR-4 High Tg	4.80	Core
Bottom Layer	<GBL>	2.8mil	FR-4 High Tg	4.80	Core
Bottom Solder Mask	<GBS>	0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
96.25 MM X 82 MM

Number of Layers : 2
MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 8 MIL
MIN. VIA DRILL SIZE: 10 MIL

MINIMUM ANNUAL RING 0.110mm (<4.37 MIL>EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER

THICKNESS: 63 MIL (1.6mm) +/-10% OTHER

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

COPPER THICKNESS (FINISHED):
OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
REFERENCE: AS SHOWN NC_DRILL FILES
PTH MIN COPPER THICKNESS: 1MIL OTHER

BOARD FINISH:
SILKSCREEN: TOP BOTTOM
SILKSCREEN COLOR: WHITE OTHER
SOLDER RESIST COLOR:
 GREEN BLUE OTHER

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPG
 1MM TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs
TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES NO
MICROSECTION: YES IMPEDANCE CONTROL: YES NO
BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
MANUFACTURER'S UL: RAL METAL SILK



PROJECT TITLE:
60W,High Efficiency Industrial Power Supply

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00702-RevB.PcbDoc

ENGINEER:
Latif Ameer

LAYOUT BY:
Manjunatha T N

SCALE: 1.00

ALTIUM DESIGNER VERSION:
14.3.14.34663

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00702	REV: RevB	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing For (Bottom Layer) (Bottom Layer)	DATE: 12/3/2015	TIME: 5:35:35 PM	TEXAS INSTRUMENTS

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